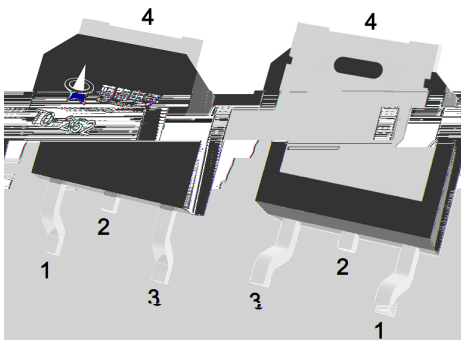
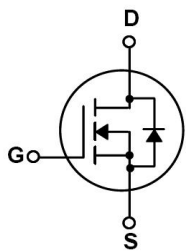
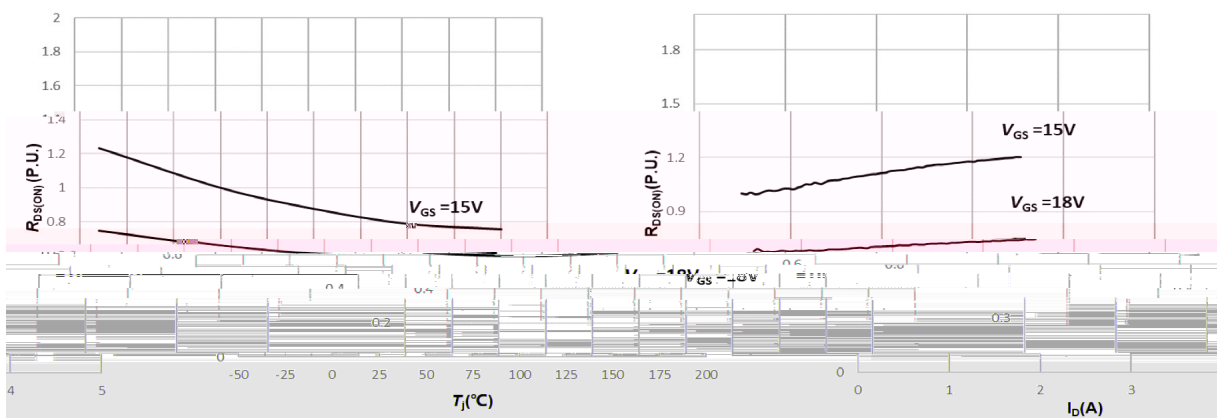
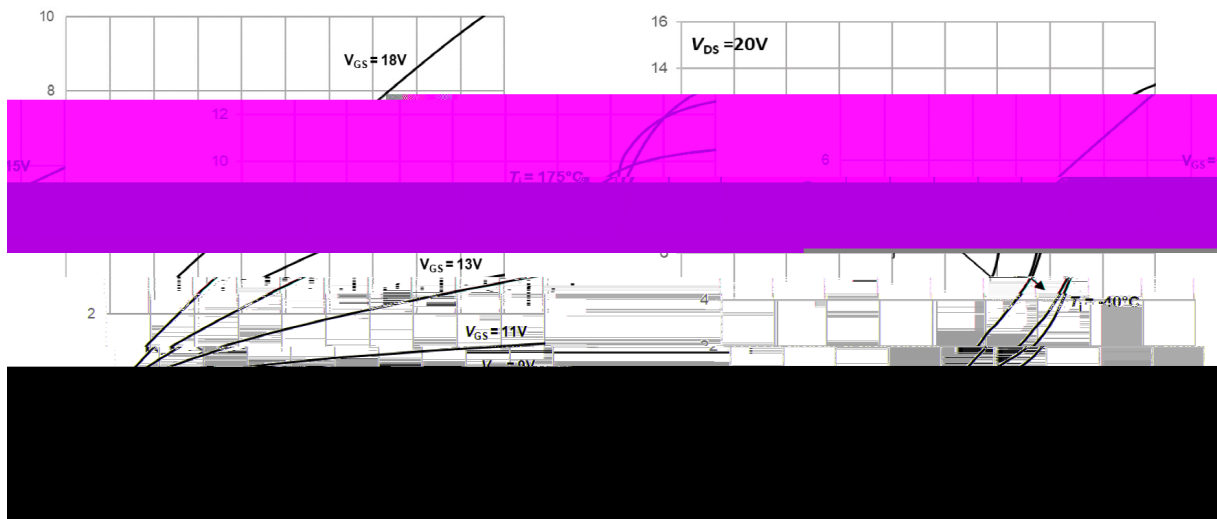
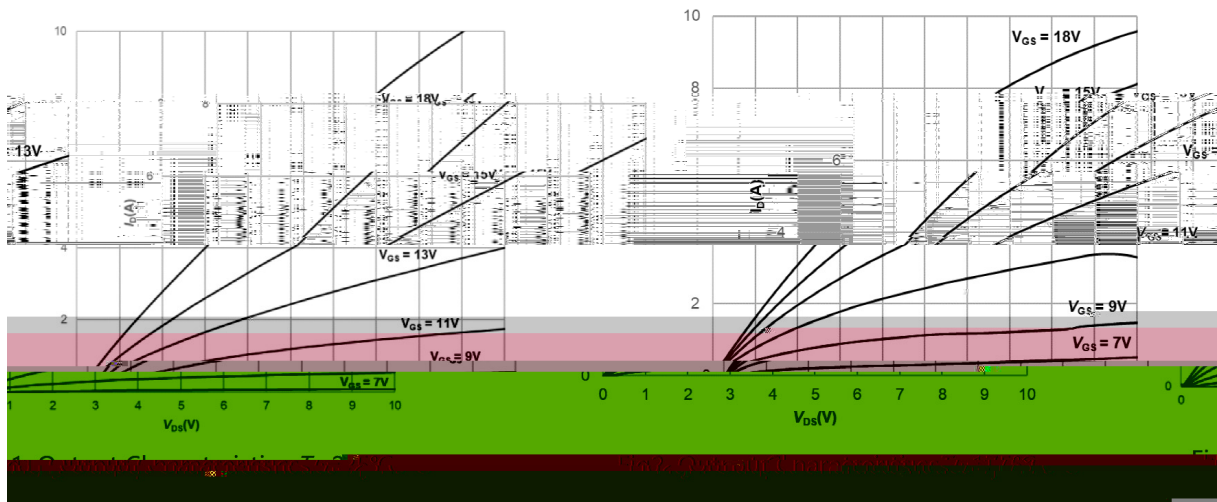


$\leq \quad \Omega \quad \Omega$





vs. Drain

Fig5. Normalized On-Resistance vs. Temperature

Fig6. Normalized On-Resistance

Current For $T_j = 25^{\circ}\text{C}$

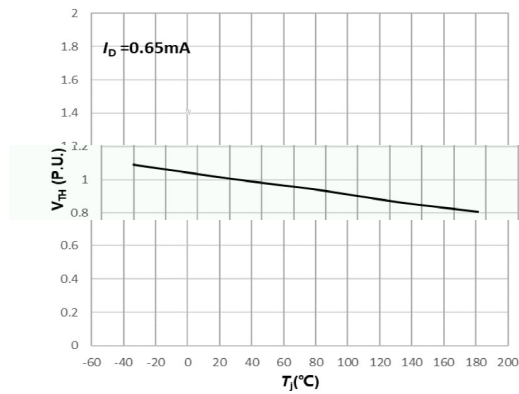


Fig. 6. Normalized Threshold Voltage vs. Temperature

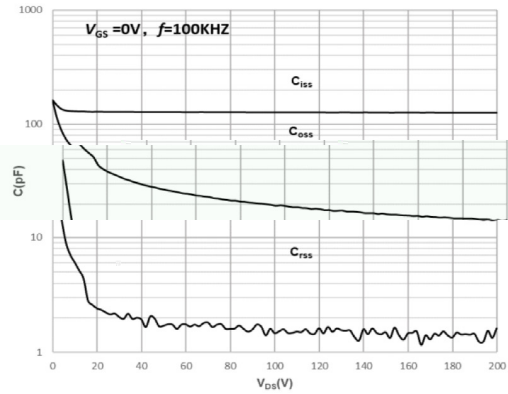


Fig. 7. Capacitances vs. Drain-Source Voltage (0-200V)

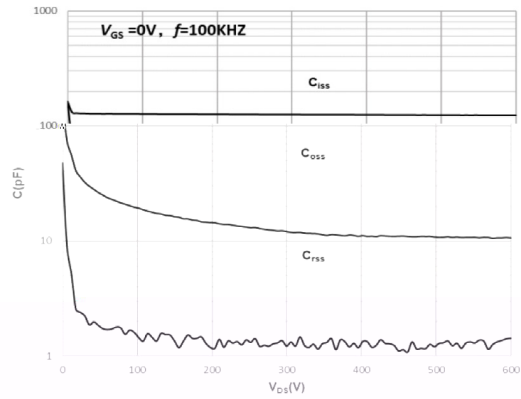


Fig. 8. Capacitances vs. Drain-Source Voltage (0-600V)

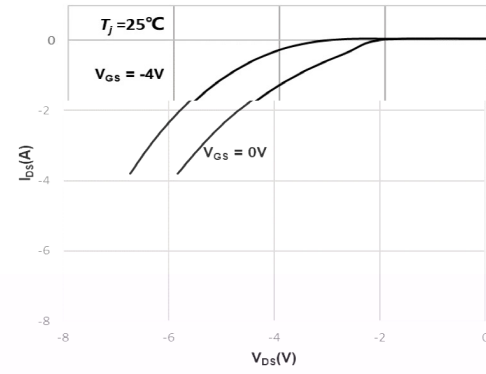


Fig. 9. Pulsed Idsat Characteristics

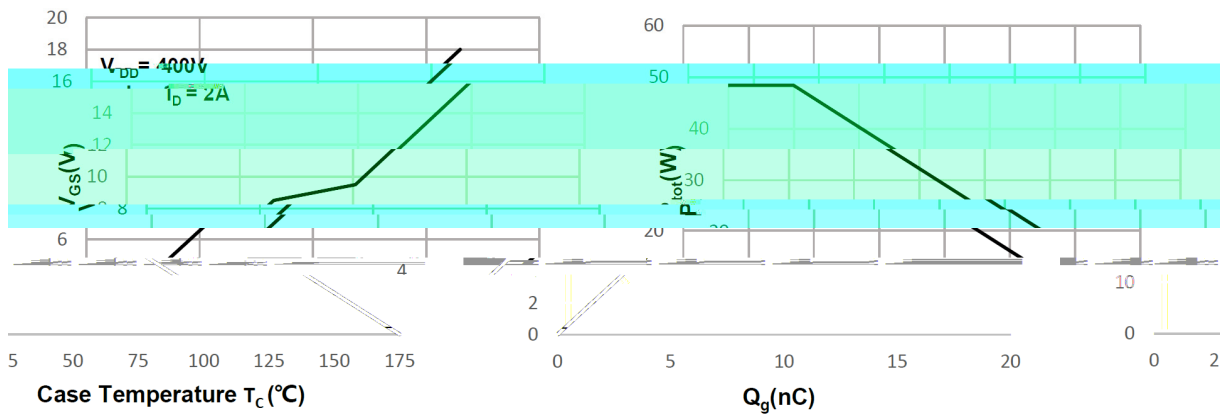


Fig. 10. Power Dissipation vs. Case temperature

Fig. 11. Gate Charge Characteristics

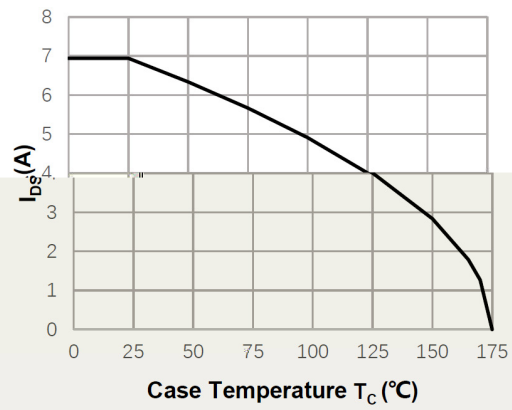
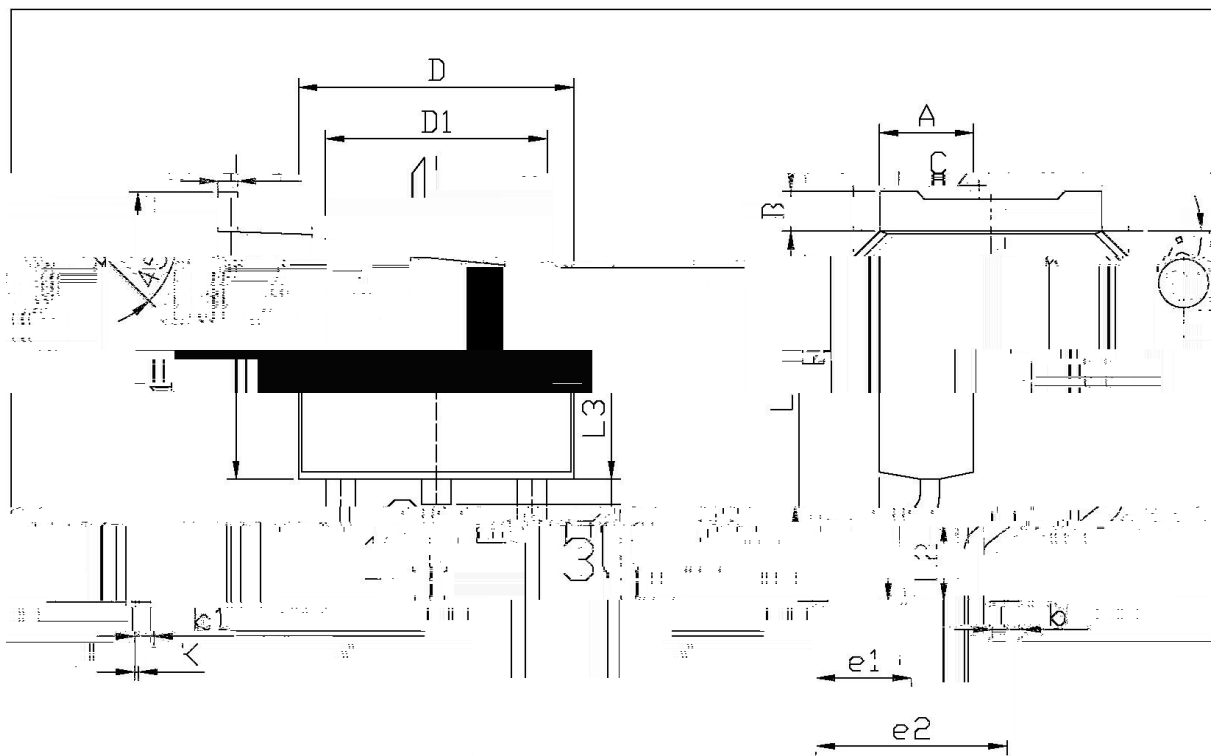


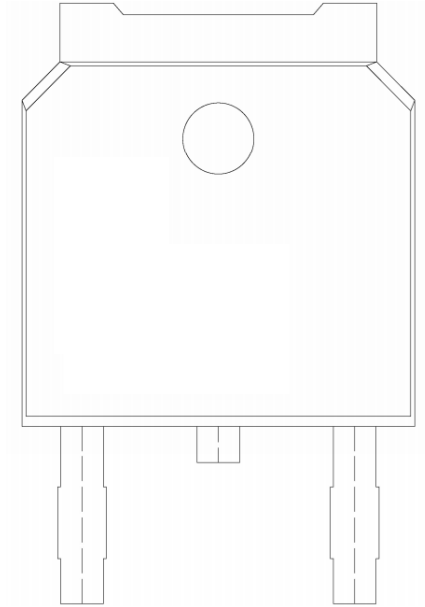
Fig13. Continuous Drain Current vs. Case Temperature



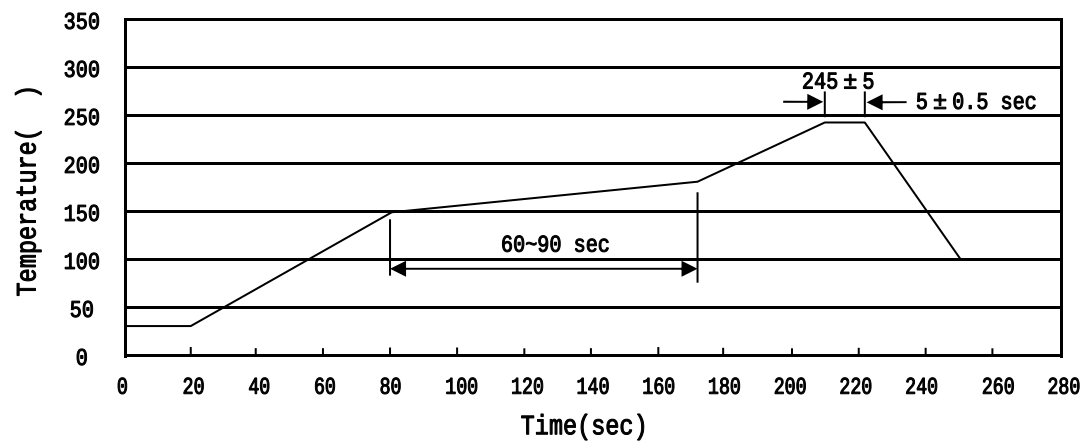
单位: mm

Symbol		Dimensions In Millimeters		Symbol		Dimensions In Millimeters	
		Min	Max			Min	Max
6.25				2.20		2.40	
2.24		2.34		0.95		1.25	
4.63		4.54		0.30		0.60	
0.45		0.55		9.85		10.35	
0.45		0.55		1.2		1.70	
0.60		0.90		6.45		6.75	
5.50		0.00	0.10	0.10		5.10	

T0-252



Temperature Profile for IR Reflow Soldering(Pb-Free)



	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box

	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Tube	Inner Box	Outer Box